

Semiconductor Packaging Market by Type (Flip-Chip, Embedded Die, Fan-In WLP, and Fan-Out WLP), Packaging Material (Organic Substrate, Bonding Wire, Leadframe, Ceramic Package, Die Attach Material, and Others), Wafer Material (Simple Semiconductor (Silicon (Si) and Germanium (Ge)) and Compound Semiconductor (III-V (Gallium Arsenide (GaAs), Indium Phosphide (InP), Gallium Nitride (GaN), Gallium Phosphide (GaP), and Others), II-VI (Zinc Sulfide (ZnS) and Zinc Selenide (ZnSe)), and IV-IV (Silicon Carbide (SiC) and Silicon-Germanium (SiGe)), and Technology (Grid Array, Small Outline Package, Flat No-Leads Packages (Dual-flat no-leads (DFN) and Quad-flat no-leads (QFN)), Dual In-Line Package (Plastic Dual Inline Package (PDIP) and Ceramic Dual Inline Package (CDIP)), and Others), and Industry Vertical (Consumer Electronics, Automotive, Healthcare, IT & Telecommunication, Aerospace & Defense, and Others): Global Opportunity Analysis and Industry Forecast, 2021–2030

<https://marketpublishers.com/r/SA4D28184AB6EN.html>

Date: June 2021

Pages: 425

Price: US\$ 6,169.00 (Single User License)

ID: SA4D28184AB6EN

Abstracts

The global semiconductor packaging market is expected to reach \$60.44 billion by 2030 from \$27.10 billion in 2020, growing at a CAGR of 9.10% from 2021 to 2030.

Semiconductor packaging refers to the material that contains a semiconductor device. This package is a case that surrounds the circuit material to protect it from corrosion or physical damage and allow mounting of the electrical contacts connecting it to the printed circuit board (PCB). With rapid growth in the semiconductor packaging market, specifically fan out wafer level packaging along with increasing demand for smartphone and devices and Internet of Things (IoT), packaging suppliers are developing processes and ways to reduce the overall cost of advanced packaging and provide maximum operational efficiency. During recent times, packaging is mainly used for high-end products and for applications related to niche-market, such as wafer and die production, due to its high cost in its operation.

The prominent factors that drive the growth of the semiconductor packaging market include growth of Internet of Things (IoT) technology, high adoption of consumer electronics devices, and evolving trends toward semiconductor wafers in the automotive industry. However, high cost associated with semiconductor packaging materials hampers its adoption, which is expected to pose a major threat to the global semiconductor packaging market. However, evolving trends toward the fan-out wafer level packaging are expected to provide lucrative opportunities to the market growth.

The global semiconductor packaging is segmented into type, packaging material, wafer material, technology, industry vertical, and region. Based on type, the market is divided into flip-chip, embedded die, fan-in WLP, and fan-out WLP. On the basis of packaging material, it is analyzed across organic substrate, bonding wire, leadframe, ceramic package, die attach material, and others. On the basis of wafer material, it is fragmented into simple semiconductor and compound semiconductor. Simple semiconductor is further sub-segmented into silicon (Si) and germanium (Ge). Compound semiconductor is further sub-segmented into III-V (Gallium Arsenide (GaAs), Indium Phosphide (InP), Gallium Nitride (GaN), Gallium Phosphide (GaP), and others), II-VI (Zinc Sulfide (ZnS) and Zinc Selenide (ZnSe)), and IV-IV (Silicon Carbide (SiC) and Silicon-Germanium (SiGe)). Based on technology, the market is categorized into grid array, small outline package, flat no-leads packages (Dual-flat no-leads (DFN) & Quad-flat no-leads (QFN)), dual in-line package (Plastic Dual Inline Package (PDIP) & Ceramic Dual Inline Package (CDIP)), and others.

By industry vertical, the market is studied across consumer electronics, automotive, healthcare, IT & telecommunication, aerospace & defense, and others. The automotive

segment accounted for the highest market share in 2020, whereas the consumer electronics segment is expected to grow at the highest CAGR from 2021 to 2030. By region, the semiconductor packaging market trends are analyzed across the North America, Europe, Asia-Pacific, and LAMEA.

KEY MARKET SEGMENTS

BY TYPE

Flip Chip

Embedded DIE

Fan-in WLP

Fan-out WLP

BY PACKAGING MATERIAL

Organic Substrate

Bonding Wire

Leadframe

Ceramic Package

Die Attach Material

Others

BY WAFER MATERIAL

Simple Semiconductor

Silicon (Si)

Germanium (Ge)

Compound Semiconductor

III-V

Gallium Arsenide (GaAs)

Indium Phosphide (InP)

Gallium Nitride (GaN)

Gallium phosphide (GaP)

Others

II-VI

Zinc Sulfide (ZnS)

Zinc Selenide (ZnSe)

IV-IV

Silicon Carbide (SiC)

Silicon-Germanium (SiGe)

BY TECHNOLOGY

Grid Array

Small Outline Package

Flat no-leads packages

Dual-flat no-leads (DFN)

Quad-flat no-leads (QFN)

Dual In-Line Package

Plastic Dual Inline Package (PDIP)

Ceramic Dual Inline Package (CDIP)

Others

BY END USER

Consumer Electronics

Automotive

Healthcare

IT & Telecommunication

Aerospace & Defense

Others

BY REGION

North America

U.S.

Canada

Mexico

Europe

UK

Germany

France

Italy

Rest of Europe

Asia-Pacific

China

Japan

India

South Korea

Taiwan

Rest of Asia-Pacific

LAMEA

Latin America

Middle East & Africa

KEY PLAYERS

Amkor Technology, Inc.

ASE Group

ChipMOS Technologies, Inc.

Powertech Technology, Inc.

Fujitsu Ltd.

Intel Corporation

Texas Instruments

Jiangsu Changjiang Electronics Technology Co., LTD

Samsung Electronics Co., Ltd.

Taiwan Semiconductor Manufacturing Company

Contents

CHAPTER 1:INTRODUCTION

- 1.1.Report description
- 1.2.Key benefits for stakeholders
- 1.3.Key market segments
- 1.4.Research methodology
 - 1.4.1.Primary research
 - 1.4.2.Secondary research
 - 1.4.3.Analyst tools and models

CHAPTER 2:EXECUTIVE SUMMARY

- 2.1.Key findings
 - 2.1.1.Top impacting factors
 - 2.1.2.Top investment pockets
- 2.2.CXO perspective

CHAPTER 3:MARKET OVERVIEW

- 3.1.Market definition and scope
- 3.2.Key forces shaping the semiconductor packaging
- 3.3.Patent analysis
 - 3.3.1.By region, 2012–2020
 - 3.3.2.By applicant, 2012–2020
- 3.4.Covid-19 impact analysis
 - 3.4.1.COVID-19 outbreak
 - 3.4.2.Impact on market size
 - 3.4.3.End user trends, preferences, and budget impact
 - 3.4.4.Parent industry impact
 - 3.4.5.Opportunity window
- 3.5.Market dynamics
 - 3.5.1.Drivers
 - 3.5.1.1.Surging Internet of Things (IoT) technology
 - 3.5.1.2.High adoption of consumer electronics devices
 - 3.5.1.3.Evolving trends toward semiconductor wafers in the automotive industry
 - 3.5.2.Restraint
 - 3.5.2.1.High-cost associated with semiconductor materials

3.5.3.Opportunity

3.5.3.1.Evolving trends towards the fan-out wafer level packaging

CHAPTER 4:SEMICONDUCTOR PACKAGING MARKET , BY PACKAGING PLATFORM

4.1.Overview

4.2.Flip Chip

4.2.1.Key market trends, growth factors, and opportunities

4.2.2.Market size and forecast, by region

4.2.3.Market analysis, by country

4.3.Embedded die

4.3.1.Key market trends, growth factors, and opportunities

4.3.2.Market size and forecast, by region

4.3.3.Market analysis, by country

4.4.Fan-in WLP

4.4.1.Key market trends, growth factors, and opportunities

4.4.2.Market size and forecast, by region

4.4.3.Market analysis, by country

4.5.Fan-out WLP

4.5.1.Key market trends, growth factors, and opportunities

4.5.2.Market size and forecast, by region

4.5.3.Market analysis, by country

CHAPTER 5:SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL

5.1.Overview

5.2.Organic Substrate

5.2.1.Key market trends, growth factors, and opportunities

5.2.2.Market size and forecast, by region

5.2.3.Market analysis, by country

5.3.Bonding-Wire

5.3.1.Key market trends, growth factors, and opportunities

5.3.2.Market size and forecast, by region

5.3.3.Market analysis, by country

5.4.Leadframe

5.4.1.Key market trends, growth factors, and opportunities

5.4.2.Market size and forecast, by region

- 5.4.3. Market analysis, by country
- 5.5. Ceramic Package
 - 5.5.1. Key market trends, growth factors, and opportunities
 - 5.5.2. Market size and forecast, by region
 - 5.5.3. Market analysis, by country
- 5.6. Die-Attach Material
 - 5.6.1. Key market trends, growth factors, and opportunities
 - 5.6.2. Market size and forecast, by region
 - 5.6.3. Market analysis, by country
- 5.7. Others
 - 5.7.1. Key market trends, growth factors, and opportunities
 - 5.7.2. Market size and forecast, by region
 - 5.7.3. Market analysis, by country

CHAPTER 6: SEMICONDUCTOR PACKAGING MARKET , BY WAFER MATERIAL

- 6.1. Overview
- 6.2. Simple Semiconductor
 - 6.2.1. Key market trends, growth factors, and opportunities
 - 6.2.2. Market size and forecast, by region
 - 6.2.2.1. Silicon (Si)
 - 6.2.2.2. Germanium (Ge)
 - 6.2.3. Market analysis, by country
- 6.3. Compound Semiconductor
 - 6.3.1. Key market trends, growth factors, and opportunities
 - 6.3.2. Market size and forecast, by region
 - 6.3.2.1. III–V Compound Semiconductor
 - 6.3.2.1.1. Gallium Arsenide (GaAs)
 - 6.3.2.1.2. Indium Phosphide (InP)
 - 6.3.2.1.3. Gallium Nitride (GaN)
 - 6.3.2.1.4. Gallium phosphide (GaP)
 - 6.3.2.1.5. Others
 - 6.3.2.2. II-VI Compound Semiconductor
 - 6.3.2.2.1. Zinc Sulfide (ZnS)
 - 6.3.2.2.2. Zinc Selenide (ZnSe)
 - 6.3.2.3. IV-IV Compound Semiconductor
 - 6.3.2.3.1. Silicon carbide (SiC)
 - 6.3.2.3.2. Silicon-Germanium (SiGe)
 - 6.3.3. Market analysis, by country

CHAPTER 7: SEMICONDUCTOR PACKAGING, BY TECHNOLOGY

7.1. Overview

7.2. Grid Array Package

7.2.1. Key market trends, growth factors, and opportunities

7.2.2. Market size and forecast, by region

7.2.3. Market analysis, by country

7.3. Small Outline Package

7.3.1. Key market trends, growth factors, and opportunities

7.3.2. Market size and forecast, by region

7.3.3. Market analysis, by country

7.4. Flat No-Leads Package

7.4.1. Key market trends, growth factors, and opportunities

7.4.2. Market size and forecast, by region

7.4.2.1. Dual Flat No-Leads (DFN) Package

7.4.2.2. Quad Flat No-Leads (QFN) Package

7.4.3. Market analysis, by country

7.5. Dual In-Line Package

7.5.1. Key market trends, growth factors, and opportunities

7.5.2. Market size and forecast, by region

7.5.2.1. Plastic Dual In-line Package (PDIP)

7.5.2.2. Ceramic Dual Inline Package (CDIP)

7.5.3. Market analysis, by country

7.6. Others

7.6.1. Key market trends, growth factors, and opportunities

7.6.2. Market size and forecast, by region

7.6.3. Market analysis, by country

CHAPTER 8: SEMICONDUCTOR PACKAGING, BY INDUSTRY VERTICAL

8.1. Overview

8.2. Consumer electronics

8.2.1. Key market trends, growth factors, and opportunities

8.2.2. Market size and forecast, by region

8.2.3. Market analysis, by country

8.3. Automotive

8.3.1. Key market trends, growth factors, and opportunities

8.3.2. Market size and forecast, by region

- 8.3.3. Market analysis, by country
- 8.4. Healthcare
 - 8.4.1. Key market trends, growth factors, and opportunities
 - 8.4.2. Market size and forecast, by region
 - 8.4.3. Market analysis, by country
- 8.5. IT & Telecommunication
 - 8.5.1. Key market trends, growth factors, and opportunities
 - 8.5.2. Market size and forecast, by region
 - 8.5.3. Market analysis, by country
- 8.6. Aerospace & Defense
 - 8.6.1. Key market trends, growth factors, and opportunities
 - 8.6.2. Market size and forecast, by region
 - 8.6.3. Market analysis, by country
- 8.7. Others
 - 8.7.1. Key market trends, growth factors, and opportunities
 - 8.7.2. Market size and forecast, by region
 - 8.7.3. Market analysis, by country

CHAPTER 9: SEMICONDUCTOR PACKAGING MAREKT, BY REGION

- 9.1. Overview
- 9.2. North America
 - 9.2.1. Key market trends, growth factors, and opportunities
 - 9.2.2. Market size and forecast, by type
 - 9.2.3. Market size and forecast, by packaging material
 - 9.2.4. Market size and forecast, by wafer material
 - 9.2.5. Market size and forecast, by technology
 - 9.2.6. Market size and forecast, by industry vertical
 - 9.2.7. Market analysis, by country
 - 9.2.7.1. U.S.
 - 9.2.7.1.1. Market size and forecast, by type
 - 9.2.7.1.2. Market size and forecast, by packaging material
 - 9.2.7.1.3. Market size and forecast, by wafer material
 - 9.2.7.1.4. Market size and forecast, by technology
 - 9.2.7.1.5. Market size and forecast, by industry vertical
 - 9.2.7.2. Canada
 - 9.2.7.2.1. Market size and forecast, by type
 - 9.2.7.2.2. Market size and forecast, by packaging material
 - 9.2.7.2.3. Market size and forecast, by wafer material

- 9.2.7.2.4. Market size and forecast, by technology
- 9.2.7.2.5. Market size and forecast, by industry vertical

9.2.7.3. Mexico

- 9.2.7.3.1. Market size and forecast, by type
- 9.2.7.3.2. Market size and forecast, by packaging material
- 9.2.7.3.3. Market size and forecast, by wafer material
- 9.2.7.3.4. Market size and forecast, by technology
- 9.2.7.3.5. Market size and forecast, by industry vertical

9.3. Europe

- 9.3.1. Key market trends, growth factors, and opportunities
- 9.3.2. Market size and forecast, by type
- 9.3.3. Market size and forecast, by packaging material
- 9.3.4. Market size and forecast, by wafer material
- 9.3.5. Market size and forecast, by technology
- 9.3.6. Market size and forecast, by industry vertical
- 9.3.7. Market analysis, by country

9.3.7.1. Germany

- 9.3.7.1.1. Market size and forecast, by type
- 9.3.7.1.2. Market size and forecast, by packaging material
- 9.3.7.1.3. Market size and forecast, by wafer material
- 9.3.7.1.4. Market size and forecast, by technology
- 9.3.7.1.5. Market size and forecast, by industry vertical

9.3.7.2. UK

- 9.3.7.2.1. Market size and forecast, by type
- 9.3.7.2.2. Market size and forecast, by packaging material
- 9.3.7.2.3. Market size and forecast, by wafer material
- 9.3.7.2.4. Market size and forecast, by technology
- 9.3.7.2.5. Market size and forecast, by industry vertical

9.3.7.3. France

- 9.3.7.3.1. Market size and forecast, by type
- 9.3.7.3.2. Market size and forecast, by packaging material
- 9.3.7.3.3. Market size and forecast, by wafer material
- 9.3.7.3.4. Market size and forecast, by technology
- 9.3.7.3.5. Market size and forecast, by industry vertical

9.3.7.4. Italy

- 9.3.7.4.1. Market size and forecast, by type
- 9.3.7.4.2. Market size and forecast, by packaging material
- 9.3.7.4.3. Market size and forecast, by wafer material
- 9.3.7.4.4. Market size and forecast, by technology

- 9.3.7.4.5. Market size and forecast, by industry vertical
- 9.3.7.5. Rest of Europe
 - 9.3.7.5.1. Market size and forecast, by type
 - 9.3.7.5.2. Market size and forecast, by packaging material
 - 9.3.7.5.3. Market size and forecast, by wafer material
 - 9.3.7.5.4. Market size and forecast, by technology
 - 9.3.7.5.5. Market size and forecast, by industry vertical
- 9.4. Asia-Pacific
 - 9.4.1. Key market trends, growth factors, and opportunities
 - 9.4.2. Market size and forecast, by type
 - 9.4.3. Market size and forecast, by packaging material
 - 9.4.4. Market size and forecast, by wafer material
 - 9.4.5. Market size and forecast, by technology
 - 9.4.6. Market size and forecast, by industry vertical
 - 9.4.7. Market analysis, by country
 - 9.4.7.1. China
 - 9.4.7.1.1. Market size and forecast, by type
 - 9.4.7.1.2. Market size and forecast, by packaging material
 - 9.4.7.1.3. Market size and forecast, by wafer material
 - 9.4.7.1.4. Market size and forecast, by technology
 - 9.4.7.1.5. Market size and forecast, by industry vertical
 - 9.4.7.2. Japan
 - 9.4.7.2.1. Market size and forecast, by type
 - 9.4.7.2.2. Market size and forecast, by packaging material
 - 9.4.7.2.3. Market size and forecast, by wafer material
 - 9.4.7.2.4. Market size and forecast, by technology
 - 9.4.7.2.5. Market size and forecast, by industry vertical
 - 9.4.7.3. India
 - 9.4.7.3.1. Market size and forecast, by type
 - 9.4.7.3.2. Market size and forecast, by packaging material
 - 9.4.7.3.3. Market size and forecast, by wafer material
 - 9.4.7.3.4. Market size and forecast, by technology
 - 9.4.7.3.5. Market size and forecast, by industry vertical
 - 9.4.7.4. South Korea
 - 9.4.7.4.1. Market size and forecast, by type
 - 9.4.7.4.2. Market size and forecast, by packaging material
 - 9.4.7.4.3. Market size and forecast, by wafer material
 - 9.4.7.4.4. Market size and forecast, by technology
 - 9.4.7.4.5. Market size and forecast, by industry vertical

9.4.7.5.Taiwan

9.4.7.5.1.Market size and forecast, by type

9.4.7.5.2.Market size and forecast, by packaging material

9.4.7.5.3.Market size and forecast, by wafer material

9.4.7.5.4.Market size and forecast, by technology

9.4.7.5.5.Market size and forecast, by industry vertical

9.4.7.6.Rest of Asia-Pacific

9.4.7.6.1.Market size and forecast, by type

9.4.7.6.2.Market size and forecast, by packaging material

9.4.7.6.3.Market size and forecast, by wafer material

9.4.7.6.4.Market size and forecast, by technology

9.4.7.6.5.Market size and forecast, by industry vertical

9.5.LAMEA

9.5.1.Key market trends, growth factors, and opportunities

9.5.2.Market size and forecast, by type

9.5.3.Market size and forecast, by packaging material

9.5.4.Market size and forecast, by wafer material

9.5.5.Market size and forecast, by technology

9.5.6.Market size and forecast, by industry vertical

9.5.7.Market analysis, by country

9.5.7.1.Latin America

9.5.7.1.1.Market size and forecast, by type

9.5.7.1.2.Market size and forecast, by packaging material

9.5.7.1.3.Market size and forecast, by wafer material

9.5.7.1.4.Market size and forecast, by technology

9.5.7.1.5.Market size and forecast, by industry vertical

9.5.7.2.Middle East and Africa

9.5.7.2.1.Market size and forecast, by type

9.5.7.2.2.Market size and forecast, by packaging material

9.5.7.2.3.Market size and forecast, by wafer material

9.5.7.2.4.Market size and forecast, by technology

9.5.7.2.5.Market size and forecast, by industry vertical

CHAPTER 10:COMPETITIVE LANDSCAPE

10.1.Introduction

10.1.1.Market player positioning, 2020

10.2.Top winning strategies

10.3.Product mapping of top 10 player

- 10.4.Competitive dashboard
- 10.5.Competitive heatmap

CHAPTER 11:COMPANY PROFILES

11.1.AMKOR TECHNOLOGY

- 11.1.1.Company overview
- 11.1.2.Key executive
- 11.1.3.Company snapshot
- 11.1.4.Product portfolio
- 11.1.5.R&D expenditure
- 11.1.6.Business performance

11.2.ASE Group

- 11.2.1.Company overview
- 11.2.2.Key executives
- 11.2.3.Company snapshot
- 11.2.4.Operating business segments
- 11.2.5.Product portfolio
- 11.2.6.R&D expenditure
- 11.2.7.Business performance

11.3.FUJITSU LIMITED

- 11.3.1.Company overview
- 11.3.2.Key executive
- 11.3.3.Company snapshot
- 11.3.4.Operating business segments
- 11.3.5.Product portfolio
- 11.3.6.R&D expenditure
- 11.3.7.Business performance

11.4.TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED

- 11.4.1.Company overview
- 11.4.2.Key Executives
- 11.4.3.Company snapshot.
- 11.4.4.Product portfolio
- 11.4.5.R&D Expenditure
- 11.4.6.Business performance
- 11.4.7.Key strategic moves and developments

11.5.TEXAS INSTRUMENTS INCORPORATED

- 11.5.1.Company overview
- 11.5.2.Key Executives

- 11.5.3. Company snapshot
- 11.5.4. Operating business segments
- 11.5.5. Product portfolio
- 11.5.6. R&D Expenditure
- 11.5.7. Business performance
- 11.5.8. Key strategic moves and developments
- 11.6. ChipMOS Technology Inc.
 - 11.6.1. Company overview
 - 11.6.2. Key executives
 - 11.6.3. Company snapshot
 - 11.6.4. Operating business segments
 - 11.6.5. Product portfolio
 - 11.6.6. R&D expenditure
 - 11.6.7. Business performance
- 11.7. Intel Corporation
 - 11.7.1. Company overview
 - 11.7.2. Key executives
 - 11.7.3. Company snapshot
 - 11.7.4. Operating business segments
 - 11.7.5. Product portfolio
 - 11.7.6. R&D expenditure
 - 11.7.7. Business performance
 - 11.7.8. Key strategic moves and developments
- 11.8. Samsung Electronics Co. Ltd.
 - 11.8.1. Company overview
 - 11.8.2. Key executives
 - 11.8.3. Company snapshot.
 - 11.8.4. Operating business segments
 - 11.8.5. Product portfolio
 - 11.8.6. R&D expenditure
 - 11.8.7. Business performance
 - 11.8.8. Key strategic moves and developments
- 11.9. Powertech Technology Inc. (PTI)
 - 11.9.1. Company overview
 - 11.9.2. Key executives
 - 11.9.3. Company snapshot
 - 11.9.4. Operating business segments
 - 11.9.5. Product portfolio
 - 11.9.6. R&D expenditure

- 11.9.7. Business performance
- 11.9.8. Key strategic moves and developments
- 11.10. Jiangsu Changjiang Electronics Technology Co., LTD (JCET)
 - 11.10.1. Company overview
 - 11.10.2. Key executives
 - 11.10.3. Company snapshot
 - 11.10.4. Operating business segments
 - 11.10.5. Product portfolio
 - 11.10.6. R&D expenditure
 - 11.10.7. Business performance
 - 11.10.8. Key strategic moves and developments

List Of Tables

LIST OF TABLES

TABLE 01.GLOBAL SEMICONDUCTOR PACKAGING, BY PACKAGING PLATFORM, 2020–2030 (\$MILLION)

TABLE 02.FLIP CHIP SEMICONDUCTOR PACKAGING MARKET, BY REGION, 2020–2030 (\$MILLION)

TABLE 03.EMBEDDED DIE SEMICONDUCTOR PACKAGING, BY REGION, 2020–2030 (\$MILLION)

TABLE 04.FAN-IN WLP SEMICONDUCTOR PACKAGING MARKET, BY REGION, 2020–2030 (\$MILLION)

TABLE 05.FAN-OUT WLP SEMICONDUCTOR PACKAGING MARKET, BY REGION, 2020–2030 (\$MILLION)

TABLE 06.SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 07.SEMICONDUCTOR PACKAGING MARKET FOR ORGANIC SUBSTRATES, BY REGION, 2020–2030 (\$MILLION)

TABLE 08.SEMICONDUCTOR PACKAGING MARKET FOR BONDING-WIRE, BY REGION, 2020–2030(\$MILLION)

TABLE 09.SEMICONDUCTOR PACKAGING MARKET FOR LEADFRAMES, BY REGION, 2020–2030(\$MILLION)

TABLE 10.SEMICONDUCTOR PACKAGING FOR CERAMIC PACKAGES, BY REGION, 2020–2030(\$MILLION)

TABLE 11.SEMICONDUCTOR PACKAGING FOR DIE-ATTACH MATERIALS, BY REGION, 2020–2030(\$MILLION)

TABLE 12.SEMICONDUCTOR PACKAGING FOR OTHERS, BY REGION, 2020–2030(\$MILLION)

TABLE 13.GLOBAL SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 14.SEMICONDUCTOR PACKAGING MARKET FOR SIMPLE SEMICONDUCTOR, BY REGION, 2020–2030 (\$MILLION)

TABLE 15.SEMICONDUCTOR PACKAGING MARKET, BY SUB-SEGMENT, 2020–2030 (\$MILLION)

TABLE 16.SEMICONDUCTOR PACKAGING MARKET FOR SILICON (SI), BY REGION, 2020–2030 (\$MILLION)

TABLE 17.SEMICONDUCTOR PACKAGING MARKET FOR GERMANIUM (GE), BY REGION, 2020–2030 (\$MILLION)

TABLE 18.SEMICONDUCTOR PACKAGING MARKET FOR COMPOUND

SEMICONDUCTOR, BY REGION, 2020–2030 (\$MILLION)

TABLE 19.SEMICONDUCTOR PACKAGING MARKET, BY SUB-SEGMENT, 2020–2030 (\$MILLION)

TABLE 20.SEMICONDUCTOR PACKAGING MARKET FOR III–V COMPOUND SEMICONDUCTORS, BY REGION, 2020–2030 (\$MILLION)

TABLE 21.III–V COMPOUND SEMICONDUCTORS, BY SUB-SEGMENT, 2020–2030 (\$MILLION)

TABLE 22.SEMICONDUCTOR PACKAGING MARKET FOR II-VI COMPOUND SEMICONDUCTORS, BY REGION, 2020–2030 (\$MILLION)

TABLE 23.II-VI COMPOUND SEMICONDUCTORS, BY SUB-SEGMENT, 2020–2030 (\$MILLION)

TABLE 24.SEMICONDUCTOR PACKAGING MARKET FOR IV-IV COMPOUND SEMICONDUCTORS, BY REGION, 2020–2030 (\$MILLION)

TABLE 25.IV-IV COMPOUND SEMICONDUCTORS, BY SUB-SEGMENT, 2020–2030 (\$MILLION)

TABLE 26.GLOBAL SEMICONDUCTOR PACKAGING, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 27.SEMICONDUCTOR PACKAGING MARKET FOR GRID ARRAY PACKAGE, BY REGION, 2020–2030 (\$MILLION)

TABLE 28.SEMICONDUCTOR PACKAGING MARKET FOR SMALL OUTLINE PACKAGE, BY REGION, 2020–2030 (\$MILLION)

TABLE 29.SEMICONDUCTOR PACKAGING MARKET FOR FLAT NO-LEADS PACKAGES, BY REGION, 2020–2030 (\$MILLION)

TABLE 30.SEMICONDUCTOR PACKAGING MARKET FOR DUAL IN-LINE PACKAGE, BY REGION, 2020–2030(\$MILLION)

TABLE 31.SEMICONDUCTOR PACKAGING FOR OTHERS, BY REGION, 2020–2030(\$MILLION)

TABLE 32.SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020–2030 (\$MILLION)

TABLE 33.SEMICONDUCTOR PACKAGING MARKET FOR CONSUMER ELECTRONICS, BY REGION, 2020–2030 (\$MILLION)

TABLE 34.SEMICONDUCTOR PACKAGING FOR AUTOMOTIVE, BY REGION, 2020–2030 (\$MILLION)

TABLE 35.SEMICONDUCTOR PACKAGING MARKET FOR HEALTHCARE, BY REGION, 2020–2030 (\$MILLION)

TABLE 36.SEMICONDUCTOR PACKAGING MARKET FOR IT & TELECOMMUNICATION, BY REGION, 2020–2030 (\$MILLION)

TABLE 37.SEMICONDUCTOR PACKAGING MARKET FOR AEROSPACE & DEFENSE, BY REGION, 2020–2030 (\$MILLION)

TABLE 38.SEMICONDUCTOR PACKAGING MARKET FOR OTHERS, BY REGION, 2020–2030 (\$MILLION)

TABLE 39.SEMICONDUCTOR PACKAGING MARKET REVENUE, BY REGION, 2020–2030 (\$MILLION)

TABLE 40.NORTH AMERICA SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 41.NORTH AMERICA SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 42.NORTH AMERICA SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 43.NORTH AMERICA SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 44.NORTH AMERICA SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020–2030 (\$MILLION)

TABLE 45.U.S. SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 46.U.S. SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 47.U.S. SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 48.U.S. SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 49.U.S. SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 50.CANADA SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 51.CANADA SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 52.CANADA SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 53.CANADA SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 54.CANADA SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 55.MEXICO SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 56.MEXICO SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 57.MEXICO SEMICONDUCTOR PACKAGING MARKET, BY WAFER

MATERIAL, 2020–2030 (\$MILLION)

TABLE 58.MEXICO SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 59.MEXICO SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 60.EUROPE SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 61.EUROPE SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 62.EUROPE SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 63.EUROPE SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 64.EUROPE SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020–2030 (\$MILLION)

TABLE 65.GERMANY SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 66.GERMANY SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 67.GERMANY SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 68.GERMANY SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 69.GERMANY SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 70.UK SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 71.UK SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 72.UK SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 73.UK SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 74.UK SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 75.FRANCE SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 76.FRANCE SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 77.FRANCE SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 78.FRANCE SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 79.FRANCE SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 80.ITALY SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 81.ITALY SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 82.ITALY SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 83.ITALY SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 84.ITALY SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 85.REST OF EUROPE SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 86.REST OF EUROPE SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 87.REST OF EUROPE SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 88.REST OF EUROPE SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 89.REST OF EUROPE SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 90.ASIA-PACIFIC SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 91.ASIA-PACIFIC SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 92.ASIA-PACIFIC SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 93.ASIA-PACIFIC SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 94.ASIA-PACIFIC SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020–2030 (\$MILLION)

TABLE 95.CHINA SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 96.CHINA SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING

MATERIAL, 2020–2030 (\$MILLION)

TABLE 97.CHINA SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 98.CHINA SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 99.CHINA SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 100.JAPAN SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 101.JAPAN SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 102.JAPAN SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 103.JAPAN SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 104.JAPAN SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 105.INDIA SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 106.INDIA SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 107.INDIA SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 108.INDIA SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 109.INDIA SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 110.SOUTH KOREA SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 111.SOUTH KOREA SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 112.SOUTH KOREA SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 113.SOUTH KOREA SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 114.SOUTH KOREA SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 115.TAIWAN SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 116.TAIWAN SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 117.TAIWAN SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 118.TAIWAN SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 119.TAIWAN SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 120.REST OF ASIA-PACIFIC SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 121.REST OF ASIA-PACIFIC SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 122.REST OF ASIA-PACIFIC SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 123.REST OF ASIA-PACIFIC SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 124.REST OF ASIA-PACIFIC SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020-2030 (\$MILLION)

TABLE 125.LAMEA SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 126.LAMEA SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 127.LAMEA SEMICONDUCTOR PACKAGING MARKET, BY WAFER MATERIAL, 2020–2030 (\$MILLION)

TABLE 128.LAMEA SEMICONDUCTOR PACKAGING MARKET, BY TECHNOLOGY, 2020–2030 (\$MILLION)

TABLE 129.LAMEA SEMICONDUCTOR PACKAGING MARKET, BY INDUSTRY VERTICAL, 2020–2030 (\$MILLION)

TABLE 130.LATIN AMERICA SEMICONDUCTOR PACKAGING MARKET, BY TYPE, 2020–2030 (\$MILLION)

TABLE 131.LATIN AMERICA SEMICONDUCTOR PACKAGING MARKET, BY PACKAGING MATERIAL, 2020–2030 (\$MILLION)

TABLE 132.LATIN AMER

I would like to order

Product name: Semiconductor Packaging Market by Type (Flip-Chip, Embedded Die, Fan-In WLP, and Fan-Out WLP), Packaging Material (Organic Substrate, Bonding Wire, Leadframe, Ceramic Package, Die Attach Material, and Others), Wafer Material (Simple Semiconductor (Silicon (Si) and Germanium (Ge)) and Compound Semiconductor (III-V (Gallium Arsenide (GaAs), Indium Phosphide (InP), Gallium Nitride (GaN), Gallium Phosphide (GaP), and Others), II-VI (Zinc Sulfide (ZnS) and Zinc Selenide (ZnSe)), and IV-IV (Silicon Carbide (SiC) and Silicon-Germanium (SiGe)), and Technology (Grid Array, Small Outline Package, Flat No-Leads Packages (Dual-flat no-leads (DFN) and Quad-flat no-leads (QFN)), Dual In-Line Package (Plastic Dual Inline Package (PDIP) and Ceramic Dual Inline Package (CDIP)), and Others), and Industry Vertical (Consumer Electronics, Automotive, Healthcare, IT & Telecommunication, Aerospace & Defense, and Others): Global Opportunity Analysis and Industry Forecast, 2021–2030

Product link: <https://marketpublishers.com/r/SA4D28184AB6EN.html>

Price: US\$ 6,169.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/SA4D28184AB6EN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

**All fields are required

Customer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970